



**BRIGHTTEK**  
**BRIGHTTEK (EUROPE) LIMITED**

*Brighten up The World With LED!*



ISO 9001:2009



BSI  
 BS EN ISO 14001:2004



QC 800000 IECQ HSP98



## PRODUCT DATASHEET



- ▶ PCB / CHIP LED
- ▶ 0603 (1608) 0.75t
- ▶ Amber 605nm

Release Date: 26 May 2022 Version: A1.1

# NOA14S80BF-5MA



### 0603 0.75t Series



#### FEATURES:

- **Package:** PCB / CHIP LED Top View
- **Forward Current:** 5mA
- **Forward Voltage (typ.):** 1.9V
- **Luminous Intensity (typ.):** 11mcd@5mA
- **Colour:** Amber
- **Wavelength (typ.):** 600~615nm
- **Viewing angle:** 50°
- **Materials:**
  - Die: AlGaInP
  - Resin: Epoxy (Black Housing)
- **Operating Temperature:** -40~+80°C
- **Storage Temperature:** -40~+100°C
- **Grouping parameters:**
  - Forward voltage
  - Luminous intensity
  - Dominant wavelength
- **Soldering methods:** Reflow
- **Preconditioning:** acc. to JEDEC Level 3
- **Packing:** 8mm tape with max.4000/reel, ø180mm (7")

#### APPLICATIONS:

- Keyboard Backlight
- Backlighting
- Indication Light
- Switch light
- Dashboard

## CHARACTERISTICS:

### Absolute Maximum Characteristics (Ta=25°C)

Parameter	Symbol	Ratings	Unit
Forward Current	I <sub>F</sub>	20	mA
Peak Forward Current Duty 1/10; width 0.1ms	I <sub>FP</sub>	80	mA
Reverse Voltage	V <sub>R</sub>	5	V
Reverse Current @5V	I <sub>R</sub>	10	μA
Power Dissipation	P <sub>D</sub>	80	mW
Electrostatic Discharge (HBM)	ESD	1000	V
Junction Temperature	T <sub>j</sub>	110	°C
Operating Temperature	T <sub>OPR</sub>	-40~+80	°C
Storage Temperature	T <sub>STG</sub>	-40~+100	°C

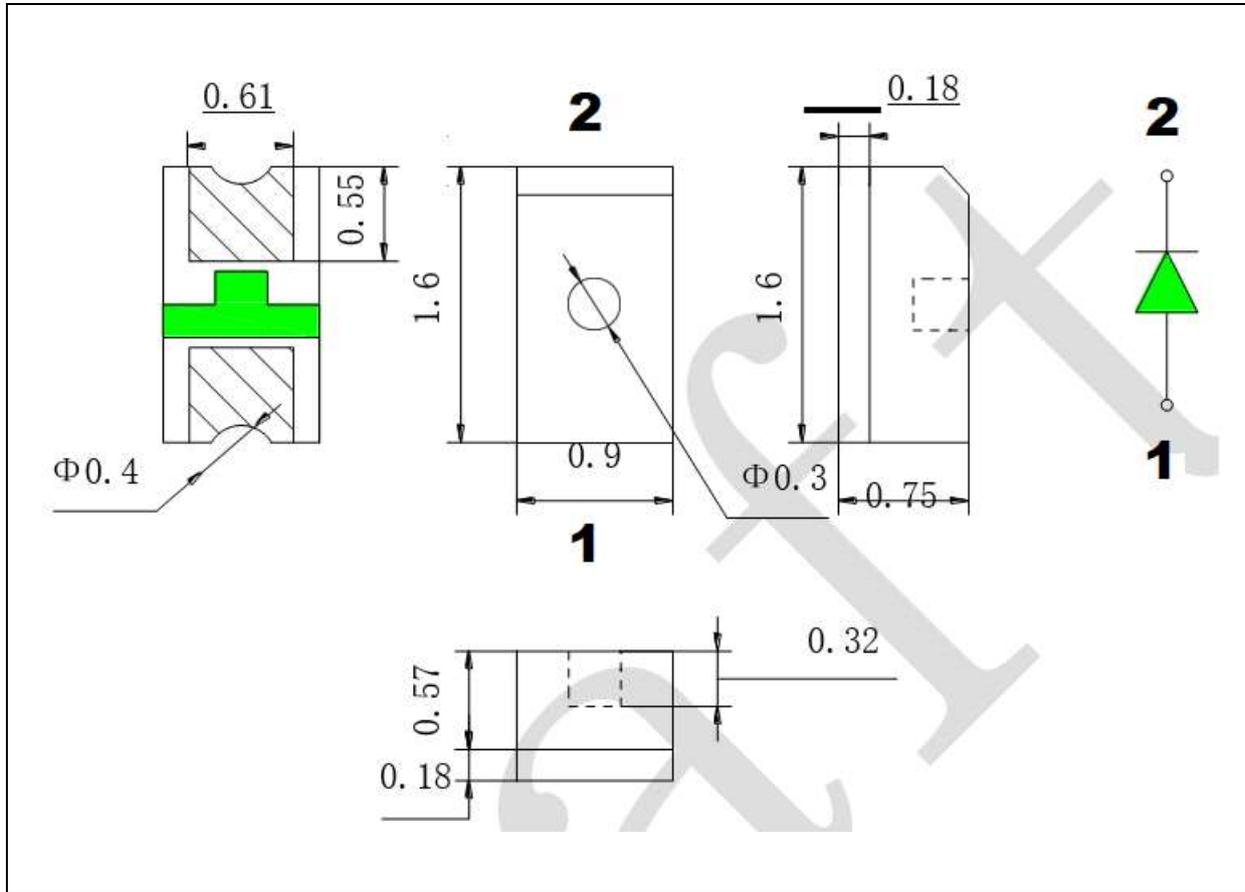
### Electrical & Optical Characteristics (Ta=25°C)

Parameter	Symbol	Values			Unit	Test Condition
		Min.	Typ.	Max.		
Forward Voltage	V <sub>F</sub>	1.6	1.9	2.5	V	I <sub>F</sub> =5mA
Luminous Intensity	I <sub>v</sub>	---	11	---	mcd	I <sub>F</sub> =5mA
Dominant Wavelength	λ <sub>D</sub>	600	---	615	nm	I <sub>F</sub> =5mA
Viewing Angle	2θ <sub>1/2</sub>	---	50	---	deg	I <sub>F</sub> =5mA

1. Luminous intensity (I<sub>v</sub>) ±10%, Forward Voltage (V<sub>F</sub>) ±0.1V, View Angle (2θ<sub>1/2</sub>) ±5%, Dominant Wavelength (λ<sub>D</sub>) ±1nm.

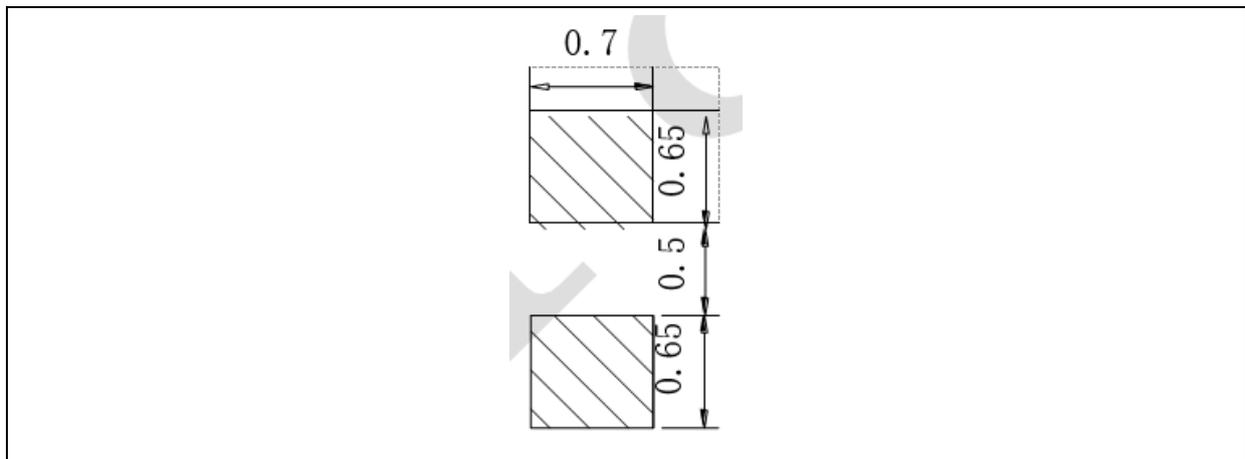
**OUTLINE DIMENSION:**

Package Dimension:



1. All dimensions are in millimetre (mm).
2. Tolerance  $\pm 0.2$ mm, unless otherwise noted.

Recommended Soldering Pad Dimension:



1. Dimensions are in millimetre (mm).
2. Tolerance  $\pm 0.1$ mm with angle tolerance  $\pm 0.5^\circ$ .

**BINNING GROUPS:**


---

 Forward Voltage Classifications ( $I_F = 5\text{mA}$ ):

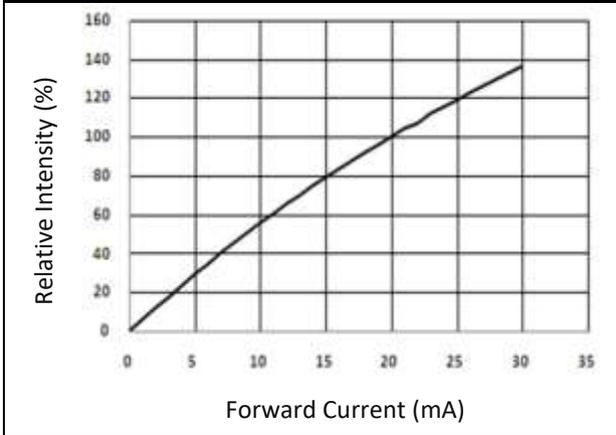
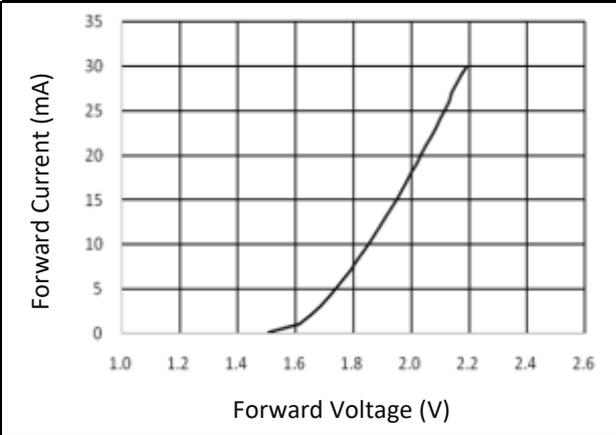
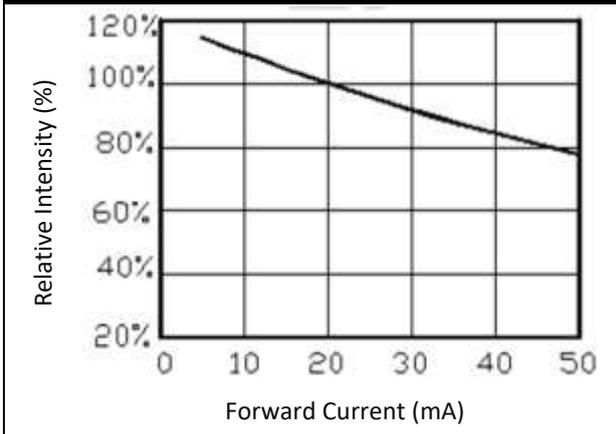
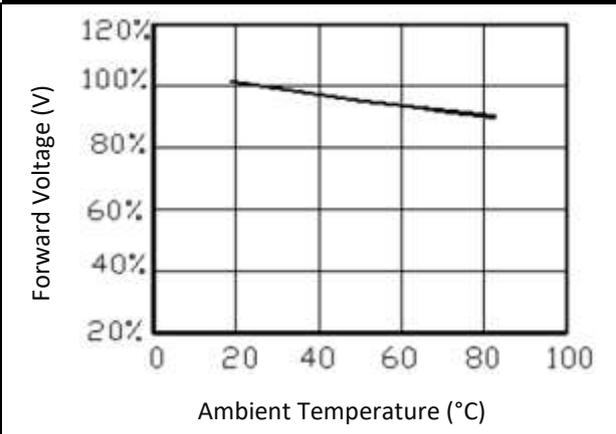
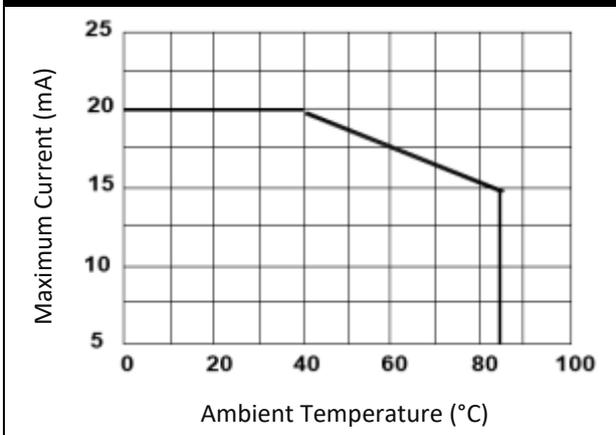
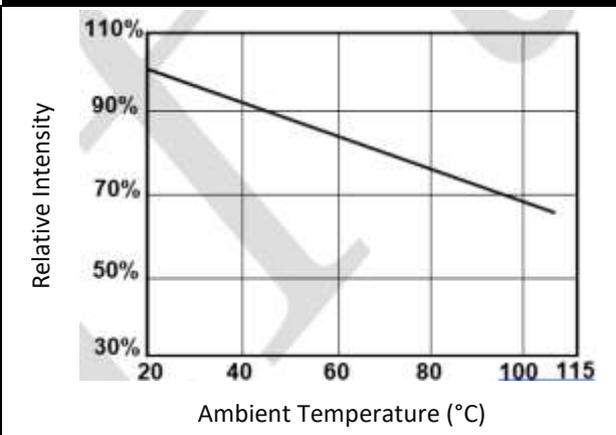
Code	Min.	Max.	Unit
b	1.6	1.9	V
c	1.9	2.2	
d	2.2	2.5	

 Luminous Intensity Classifications ( $I_F = 5\text{mA}$ ):

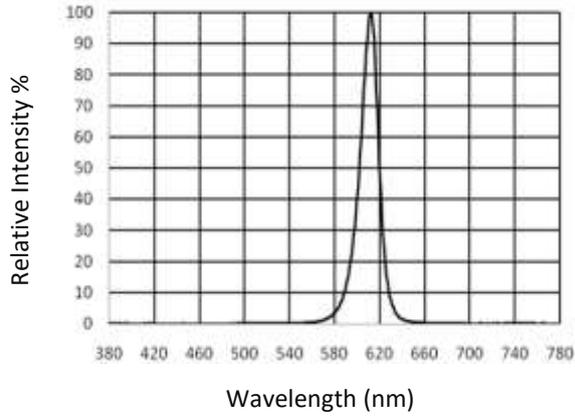
Code	Min.	Max.	Unit
8	5	8	mcd
9	8	12.5	
A	12.5	16	
B	16	20	
C	20	25	

 Dominant Wavelength Classifications ( $I_F = 5\text{mA}$ ):

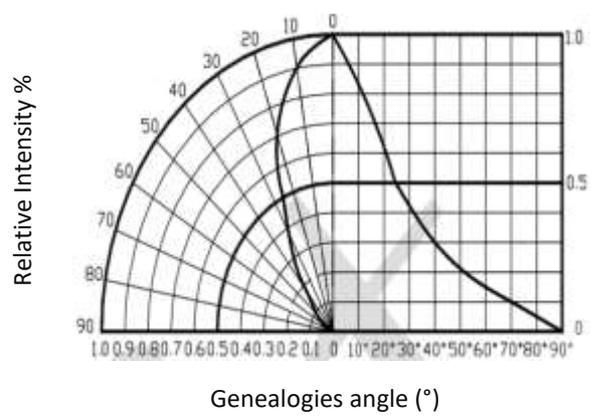
Code	Min.	Max.	Unit
p	600	605	nm
q	605	610	
r	610	615	

**ELECTRO-OPTICAL CHARACTERISTICS:**
**Relative Intensity v.s. Forward Current**

**Forward Current v.s. Forward Voltage**

**Forward Current v.s. Luminous Efficiency**

**Forward Voltage v.s. Temperature**

**Temperature Derating Chart**

**Relative Intensity Flux v.s. Junction Temperature**


Relative Intensity v.s. Wavelength

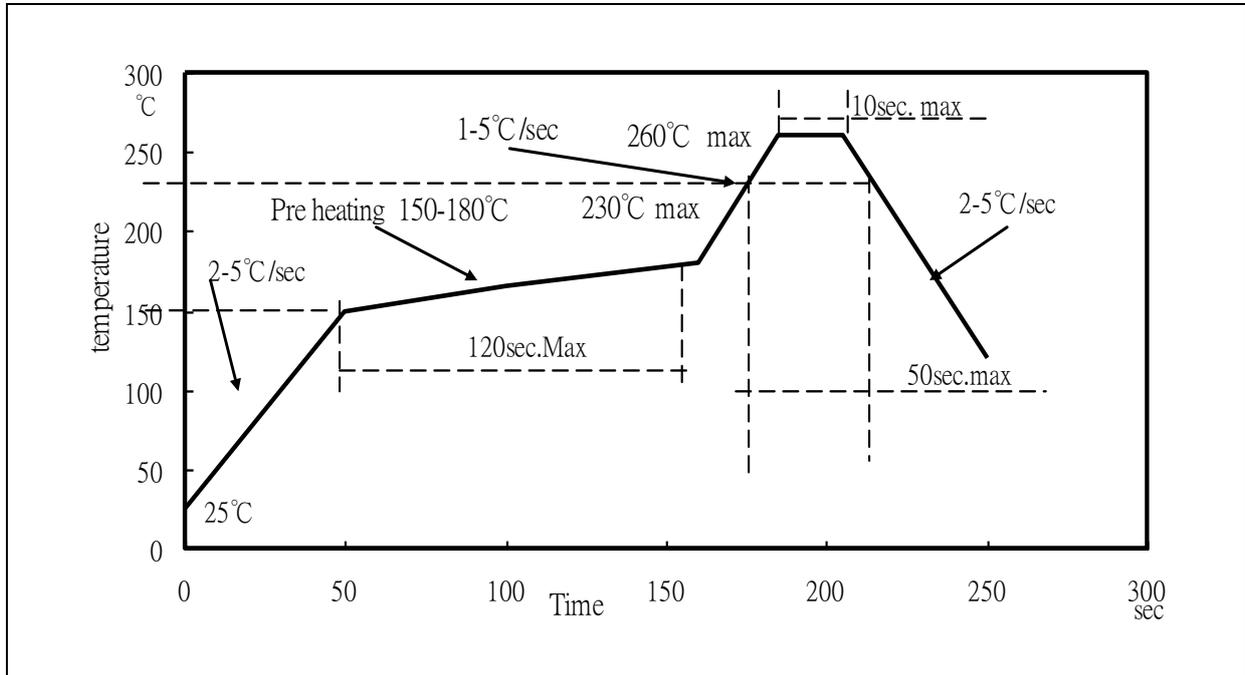


Relative Intensity v.s. Angular Displacement



## RECOMMENDED SOLDERING PROFILE:

Reflow solder:

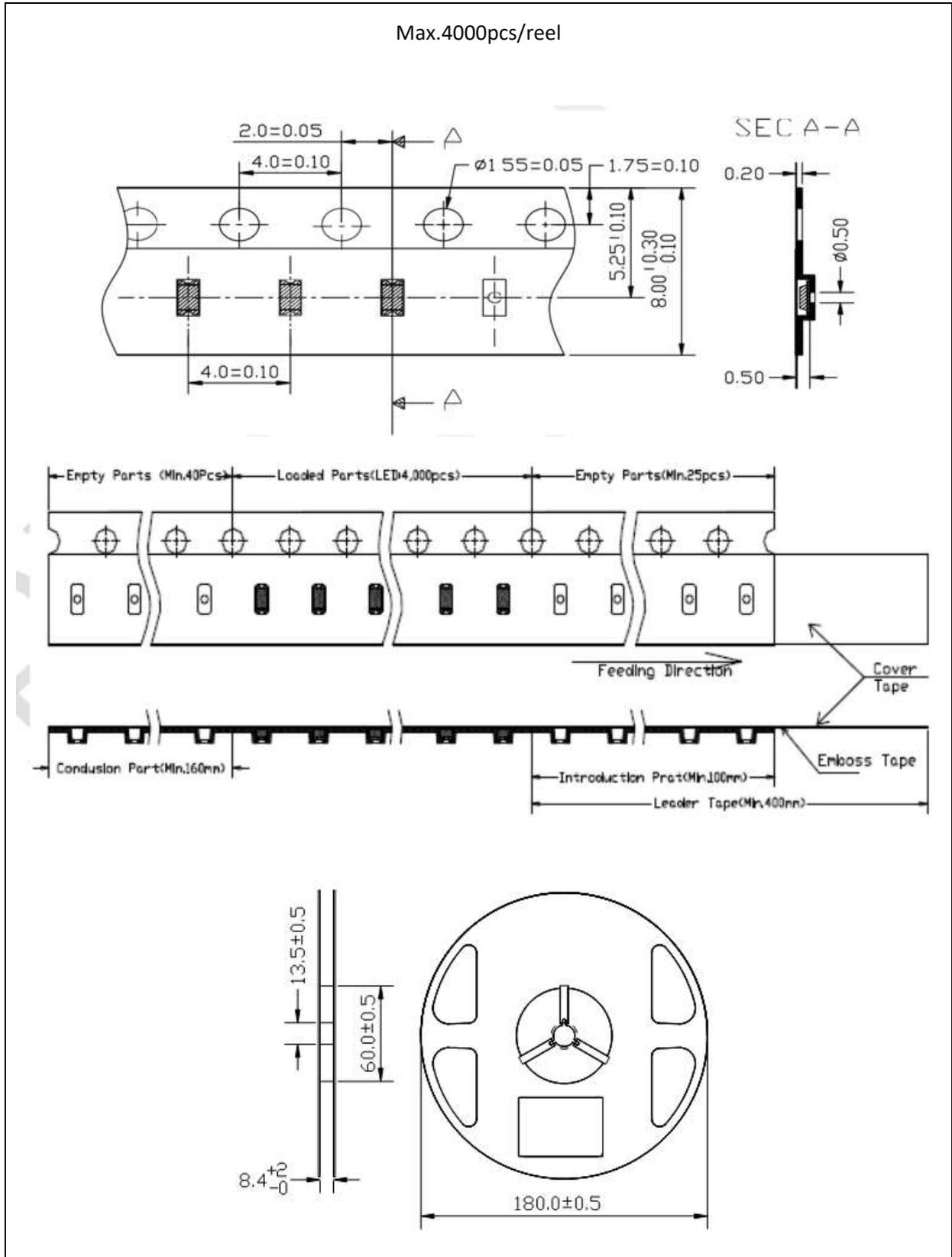


Note:

1. Recommend reflow temperature 240°C. The maximum soldering temperature should be limited to 260°C.
2. Maximum reflow soldering: 3 times.
3. Before, during, and after soldering, should not apply stress on the components and PCB board.

**PACKING SPECIFICATION:**

Reel Dimension:



## PRECAUTIONS OF USE:

---

### Storage:

It is recommended to store the products in the following conditions:

- Humidity: 60% R.H. Max.
- Temperature: 5°C~30°C (41°F ~86°F).

Shelf life in sealed bag: 12 months at 5°C~30°C and <60% R.H.

Once the package is opened, the products should be used within a week. Otherwise, they should be kept in a damp-proof box with desiccating agent <10% R.H. and apply baking before use.

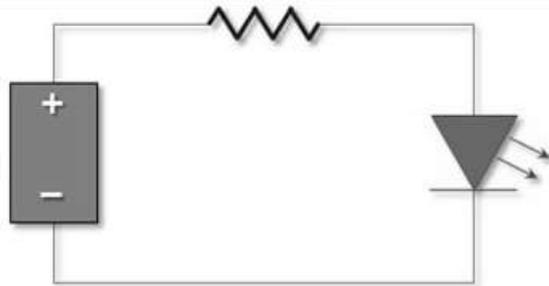
### Baking:

It is recommended to bake the LED before soldering if the pack has been unsealed for longer than 24hrs. The suggested baking conditions are as followings:

- 60±3°C x 6hrs and <5%RH, taped / reel package.

It's normal to see slight color fading of carrier (light yellow) after baking in process.

### Testing Circuit:



Must apply resistor(s) for protection (over current proof).

### Cleaning:

Use alcohol-based cleaning solvents such as isopropyl alcohol to clean the LED carrier / package. Avoid putting any stress force directly on to the LED lens.

### ESD (Electrostatic Discharge):

Static Electricity or power surge will damage the LED. Use of a conductive wrist band or anti-electrosatic glove is recommended when handling the LED all time. All devices, equipment, machinery, work tables, and storage racks must be properly grounded.

In the events of manual working in process, make sure the devices are well protected from ESD at any time.

**REVISION RECORD:**

---

Version	Date	Summary of Revision
A1.0	27/07/2016	Datasheet set-up.
A1.1	26/05/2022	New datasheet format.